The new Teseo III product family creates a new state-of-the-art in positioning accuracy by building on the industry-leading performance of ST’s Teseo II single-chip satellite-tracking ICs. The new generation also leverages the company’s investment and support for sensor fusion as found in automotive DRAW and Assisted-GNSS (Global Navigation Satellite System) functions.

KEY FEATURES
- Multiconstellation single chip receiver
- ARM946 microprocessor
- ST-AGPS support
- ST automotive grade
- The world’s richest set of interfaces/peripherals like: CAN, I²C, USB, ADC
- Update rate up to 10 Hz
- Antenna sensing
- Teseo DRAW
- AEC-Q100 qualified

KEY BENEFITS
- Accurate position
- 3D fix also in urban canyon condition
- Fast Time To First Fix (TTFF)

TARGETED APPLICATIONS
- Emergency calls (eCall and ERA-Glonass)
- In-dash navigation
- Usage-Based Insurance (UBI)
- Anti-theft
- Car to car
- Fleet management
- Road tolling
- Vehicle tracking
- Marine

The new trend in automotive applications
HIGH POSITIONING ACCURACY LEVEL

MULTICONSTELLATION CAPABILITY

DEVICE SUMMARY

<table>
<thead>
<tr>
<th>Part number</th>
<th>Teseo2 Pin to Pin compatible</th>
<th>Package</th>
<th>Memory Management</th>
</tr>
</thead>
<tbody>
<tr>
<td>STA8089FG</td>
<td>Yes</td>
<td>QFN56 7x7mm 0.4mm pitch</td>
<td>Stacked Flash</td>
</tr>
<tr>
<td>STA8090FG</td>
<td></td>
<td>BGA99 6x5mm 0.5mm pitch</td>
<td>Stacked Flash</td>
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<tr>
<td>STA8090GA/GAT*</td>
<td></td>
<td>QFN56 8x8mm 0.5mm pitch wettable flank</td>
<td>External SQI</td>
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<tr>
<td>STA8090EXG/A</td>
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<td>BGA169 9x9mm 0.65mm pitch</td>
<td>Ext. Parallel NOR &amp; RAM</td>
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</tbody>
</table>

Note: * will be released in Q3/2015